

**ABSTRACT****Manufacturing method of a system in package having several layers and associated manufacturing installation**

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The present invention relates to a method for manufacturing a system in package having several layers (SiP), comprising for each current layer the following steps:

- realization (A) of a dielectric substrate by an additive manufacturing technique ;
- 10 - deposition (B) of an adhesive in receiving zones;
- deposition (C) of electronic components in the corresponding receiving zones;
- deposition (E) of interconnection elements between the electronic components;
- creation (F) of at least one interconnection with an adjacent layer;
- encapsulation (G) the current layer with filler material, the filler material forming an
- 15 outer surface;
- preparation (H) of the outer surface for receiving the next layer.

Figure for abstract: Figure 2